

Europe Advanced Packaging Market By Type (Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2), 5D/3D and others), By End User (Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

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Abstracts

The Europe Advanced Packaging Market would witness market growth of 12.3% CAGR during the forecast period (2020-2026).

With rapid growth in the advanced packaging market, particularly in wafer level packaging, together with increased demand for smartphones and devices and the Internet of Things (IoT), advanced packaging suppliers are developing processes and ways to reduce the overall cost of advanced packaging and ensure maximum operational efficiency.

In recent times, innovative packaging is primarily used for high-end products and for niche-related applications such as wafer and die processing due to high operating costs. Different integrated circuits (ICs) have various packaging requirements that provide growth opportunities for advanced packaging over traditional packaging processes. Furthermore, advanced packaging is expected to offer higher capabilities than conventional packaging solutions, which are expected to provide lucrative opportunities for advanced packaging market trends in the coming years.

The demand for compact electronic devices has increased in almost every sector, be it communication equipment, automotive, industrial or healthcare equipment. This trend has prompted semiconductor IC manufacturers to increase R&D investment in order to reduce the size and improve the output of ICs. This led to the advent of MEMS and 3D IC chips. In addition, over the decades, ICs have often been more dense due to the growing number of interconnects and transistors requiring better deposition and

patterning.

Based on Type, the market is segmented into Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others. Based on End User, the market is segmented into Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others. Based on countries, the market is segmented into Germany, UK, France, Russia, Spain, Italy, and Rest of Europe.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include Qualcomm, Inc., Intel Corporation, IBM Corporation, Texas Instruments, Inc., Analog Devices, Inc., Renesas Electronics Corporation, Samsung Electronics Co., Ltd. (Samsung Group), Amkor Technology, Inc., Brewer Science, Inc., and MICROCHIP Technology, Inc.

Scope of the Study

Market Segmentation:

By Type

Flip-Chip Ball Grid Array

Flip Chip CSP

Wafer Level CSP

2.5D/3D

Others

By End User

Consumer Electronics

Automotive

Industrial

Aerospace & Defense

Healthcare & Life Sciences

Others

By Country

Germany

UK

France

Russia

Spain

Italy

Rest of Europe

Companies Profiled

Qualcomm, Inc.

Intel Corporation

IBM Corporation

Texas Instruments, Inc.

Analog Devices, Inc.

Renesas Electronics Corporation

Samsung Electronics Co., Ltd. (Samsung Group)

Amkor Technology, Inc.

Brewer Science, Inc.

Microchip Technology, Inc.

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